	Hit s	Search Text	DBs
36	2	(((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board) or PWB) near29 (dielectric or non\$4copper or (FR\$3 near3 insulat\$4))) and (((fill\$4 or deposit\$4 or embed\$5) near26 (via or hole or through\$4hole) near9 (capacit\$4 or dielectric or ((capacit\$4 or inorganic or resin) near9 (paste or material or composition or BaTiO\$2 or (barium near2 titanate))))) same contact\$4 same bottom same top same electrode)	
37	2	(((print\$4 near9 (wiring or circuit\$4) near9 (panel or board)) or PCB or ((circuit\$4 or wiring) near9 board) or PWB) near29 (dielectric or non\$4copper or (FR\$3 near3 insulat\$4))) and (((fil1\$4 or deposit\$4 or embed\$5) near26 (via or hole or through\$4hole) near22 (capacit\$4 or dielectric or ((capacit\$4 or inorganic or resin) near9 (paste or material or composition or BaTio\$2 or (barium near2 titanate))))) same contact\$4 same bottom same top same electrode)	US-PGPUB

	Hit s	Search Text	DBs
38		(((print\$4 near9 (wiring or circuit\$4) near9 (panel or board)) or PCB or ((circuit\$4 or wiring) near9 board) or PWB) near29 (dielectric or non\$4copper or (FR\$3 near3 insulat\$4))) and (((fill\$4 or deposit\$4 or embed\$5) near26 (via or hole or through\$4hole) near22 (capacit\$4 or dielectric or ((capacit\$4 or inorganic or resin) near9 (paste or material or composition or BaTiO\$2 or (barium near2 titanate)))) same contact\$4 same bottom same top same (electrode or (metal\$4 near12 terminal)))	US-PGPUB
39		361/748.ccls. and (((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board)) near29 (dielectric or non\$4copper)) and (((fill\$4 or deposit\$4 or embed\$5) near26 (via or hole or through\$4hole or wiring\$4board or CPC or board) near9 (capacit\$4 or	USPAT; FPRS; EPO; JPO;

	Hit	Search Text	DBs
40	0	361/763.ccls. and (((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board))) and (((fill\$4 or deposit\$4 or embed\$5) near26 (via or hole or through\$4hole or wiring\$4board or CPC or board) near9 (capacit\$4 or dielectric or ((capacit\$4 or inorganic or resin) near9 (paste or material)))) same contact\$4 same bottom same top same electrode)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
41	0	174/260.ccls. and (((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board)) near29 (dielectric or non\$4copper)) and (((fill\$4 or deposit\$4 or embed\$5) near26 (via or hole or through\$4hole or wiring\$4board or CPC or board) near9 (capacit\$4 or	USPAT; FPRS; EPO; JPO;
42	0	174/260.ccls. and (((print\$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hit s	Search Text	DBs
43	0	<pre>board) or PCB or ((circuit\$4 or wiring) near9 board))) and ((fill\$4 or filler or paste) same (via or hole or trench or</pre>	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
44		430/313.ccls. and (((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board))) and ((fill\$4 or filler or paste) same (via or hole or trench or	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
45	0	361/748.ccls. and (((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board))) and ((fill\$4 or filler or paste) same (wis or hele or trench or	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hit s	Search Text	DBs
46	5	(((fill\$4 or deposit\$4 or embed\$5) near26 (via or hole or through\$4hole) near22 (capacit\$4 or dielectric or ((capacit\$4 or	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB